

Title (en)

Electrolytic Tin Plating Solution and Electrolytic Tin Plating Method

Title (de)

Elektrolytische Zinnbeschichtungslösung und elektrolytisches Zinnbeschichtungsverfahren

Title (fr)

Solution électrolytique de plaquage d'étain et procédé électrolytique de plaquage d'étain

Publication

EP 2141261 A3 20100728 (EN)

Application

EP 09155197 A 20090316

Priority

JP 2008154461 A 20080612

Abstract (en)

[origin: EP2141261A2] A plating solution and a plating method, which does not use a complexing agent and which provides favorable solder wetting properties and an extremely low coupling rate when electrolytic tin plating is performed, and particularly when electrolytic tin plating is performed using a barrel plating method.

IPC 8 full level

C23C 18/54 (2006.01); **C25D 3/32** (2006.01)

CPC (source: EP KR US)

C25D 3/30 (2013.01 - EP KR US); **C25D 17/16** (2013.01 - EP KR US)

Citation (search report)

- [X1] EP 1754805 A1 20070221 - ROHM & HAAS ELECT MAT [US]
- [X1] US 4717460 A 19880105 - NOBEL FRED I [US], et al
- [X1] US 4135991 A 19790123 - CANARIS VALERIE M, et al
- [X1] US 2006051610 A1 20060309 - CROSBY JEFFREY N [GB]

Cited by

EP3715508A4; EP2740820A1; WO2019121092A1; US11459665B2; WO2019201753A1; US11242606B2; US11840771B2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA RS

DOCDB simple family (publication)

EP 2141261 A2 20100106; EP 2141261 A3 20100728; EP 2141261 B1 20170301; CN 101619470 A 20100106; CN 101619470 B 20120328; JP 2009299123 A 20091224; JP 5583894 B2 20140903; KR 101593475 B1 20160212; KR 20090129373 A 20091216; TW 201006966 A 20100216; TW I468554 B 20150111; US 2010000873 A1 20100107

DOCDB simple family (application)

EP 09155197 A 20090316; CN 200910146202 A 20090612; JP 2008154461 A 20080612; KR 20090051978 A 20090611; TW 98119007 A 20090608; US 45607709 A 20090611